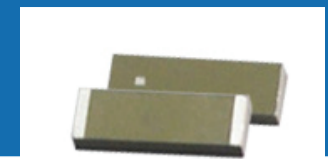




**THE DATASHEET OF
ACAG1204-915-T**



915 MHz Ceramic Chip Antenna



ACAG1204-915-T

12.0 x 4.0 x 1.6mm
RoHS/RoHS II Compliant
MSL = 1

FEATURES

- Uses Low Temperature Co-Fired Ceramic (LTCC) Technology
- Gain of 3.42 dBi
- Omnidirectional
- VSWR of ≤ 2.0

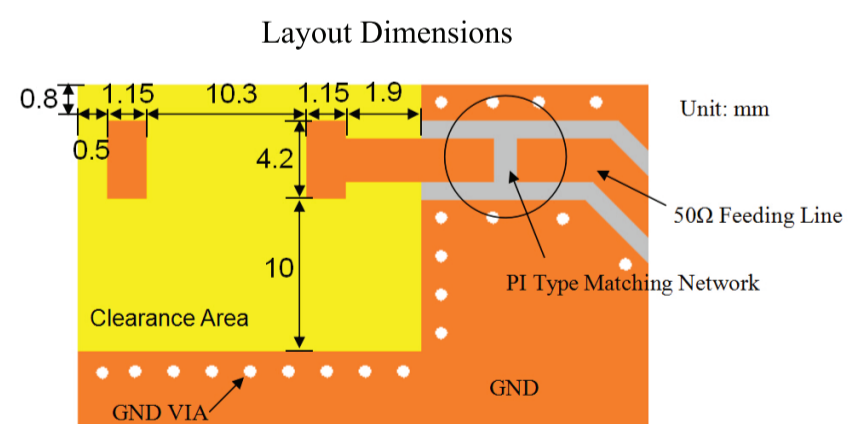
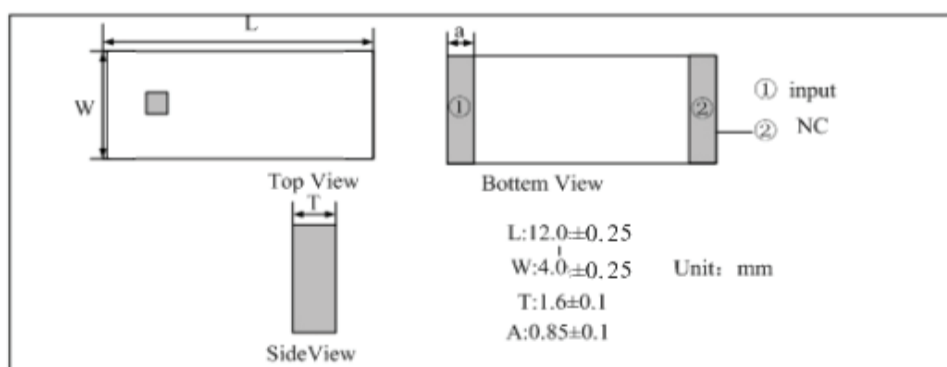
APPLICATIONS

- ISM applications
- LORA
- Sigfox
- RFID

ELECTRICAL SPECIFICATIONS

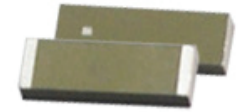
| Item | Specification |
|-----------------------------|------------------|
| Frequency | 915MHz |
| Bandwidth | 15MHz typ |
| VSWR | ≤ 2.0 |
| Impedance | 50 Ω |
| Gain | 3.42dBi |
| Azimuth | Omni-directional |
| Polarization | Linear |
| Operating Temperature range | -40°C ~+ 85°C |

DIMENSIONS



Unit: mm

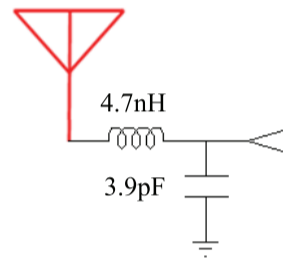
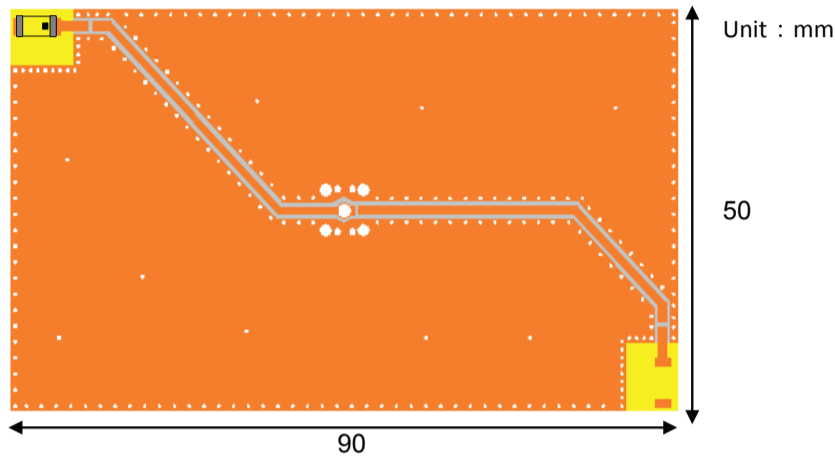
915 MHz Ceramic Chip Antenna



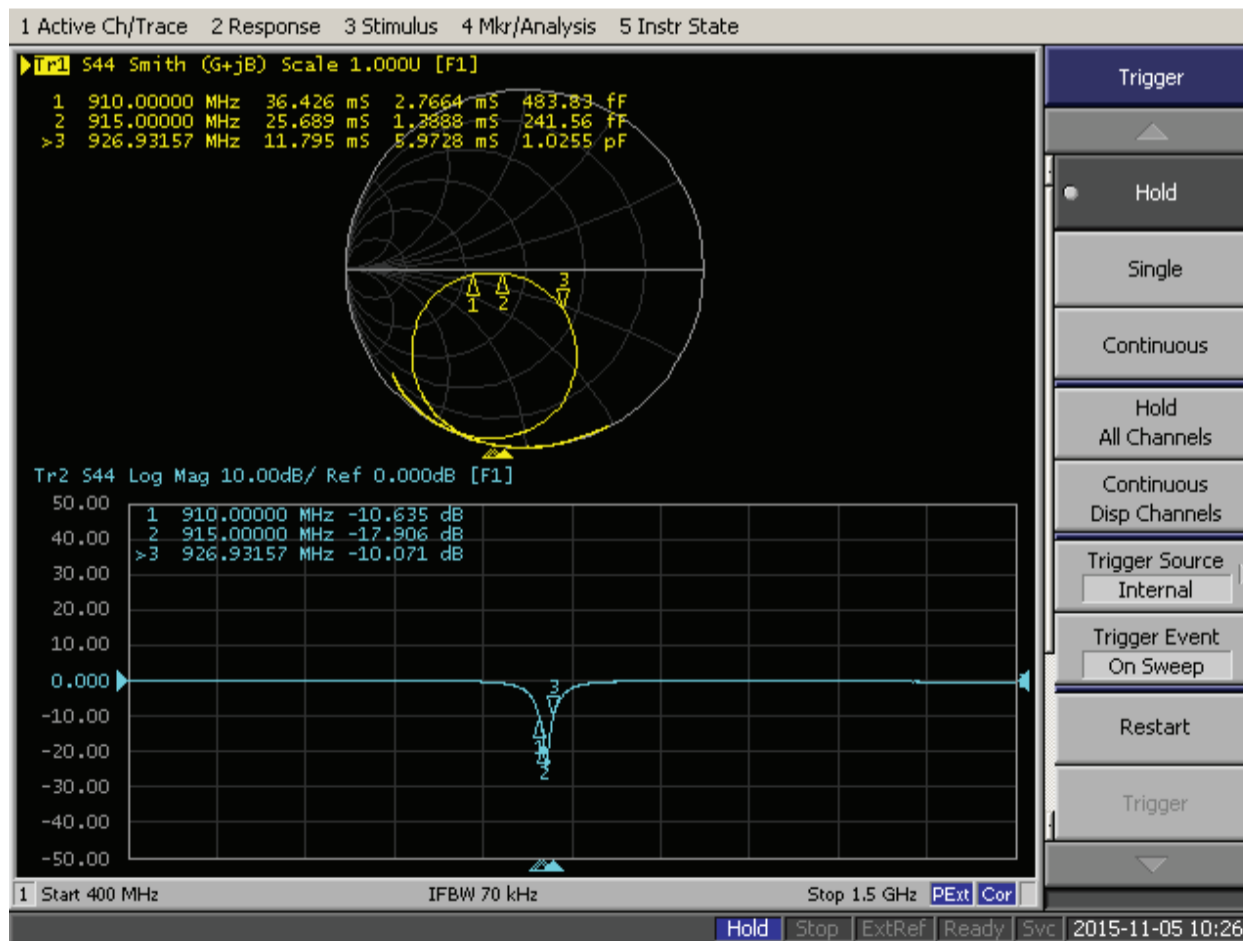
ACAG1204-915-T

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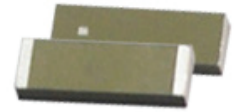
EVALUATION BOARD AND MATCHING CIRCUITS



ANTENNA RESPONSE – SMITH CHART AND RETURN LOSS S11



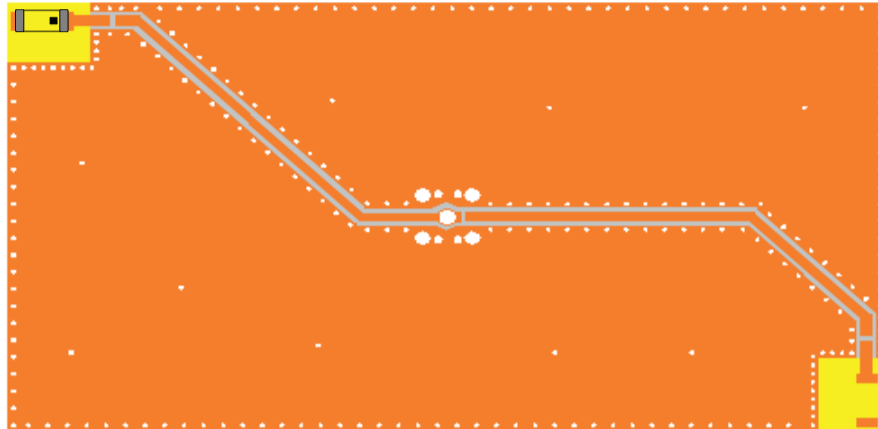
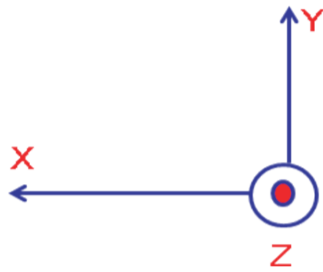
915 MHz Ceramic Chip Antenna



ACAG1204-915-T

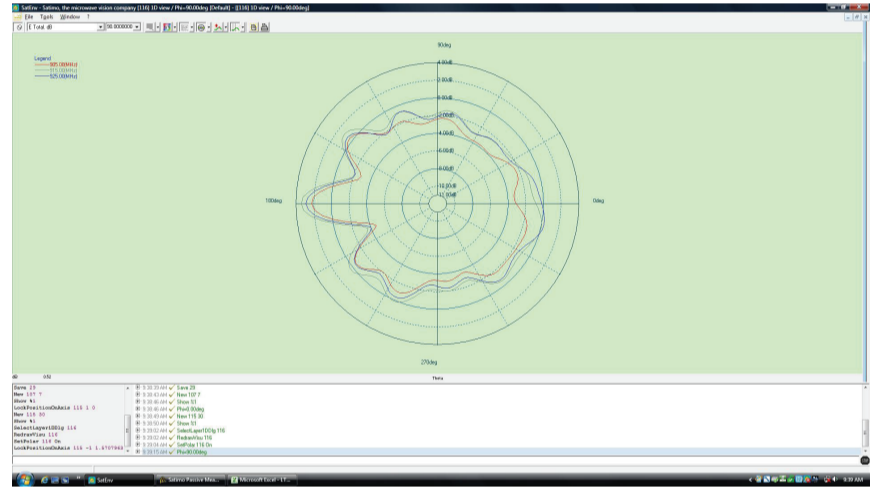
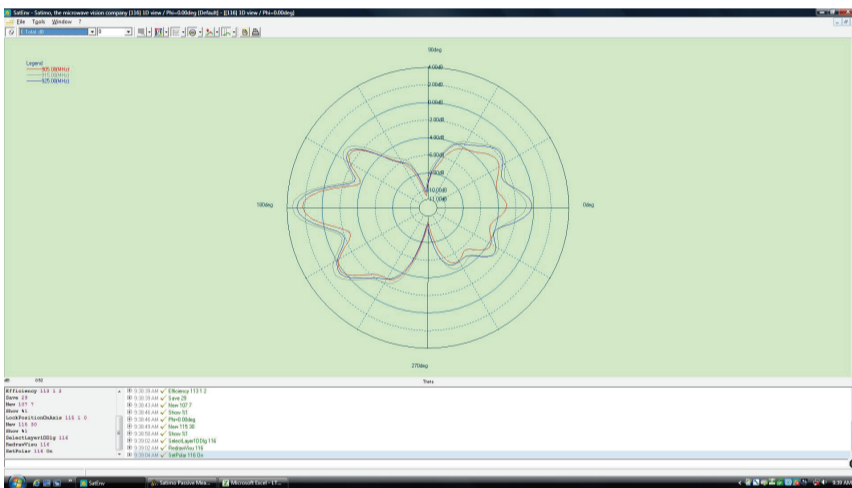
12.0 x 4.0 x 1.6mm
RoHS/RoHS II Compliant
MSL = 1

RADIATION PATTERNS

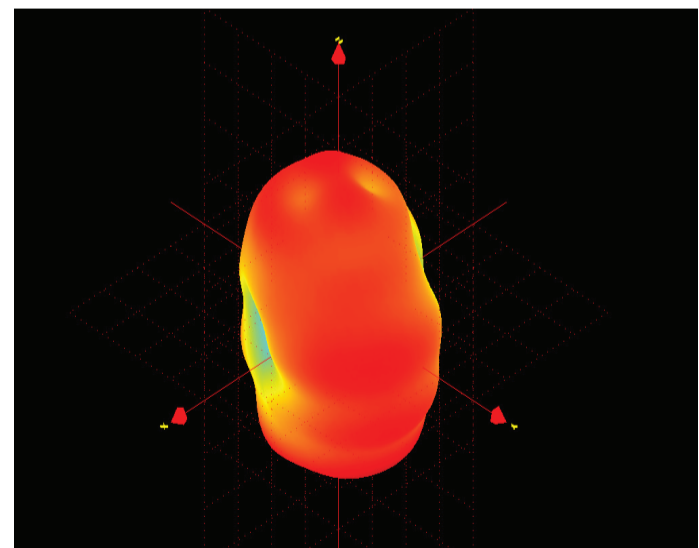
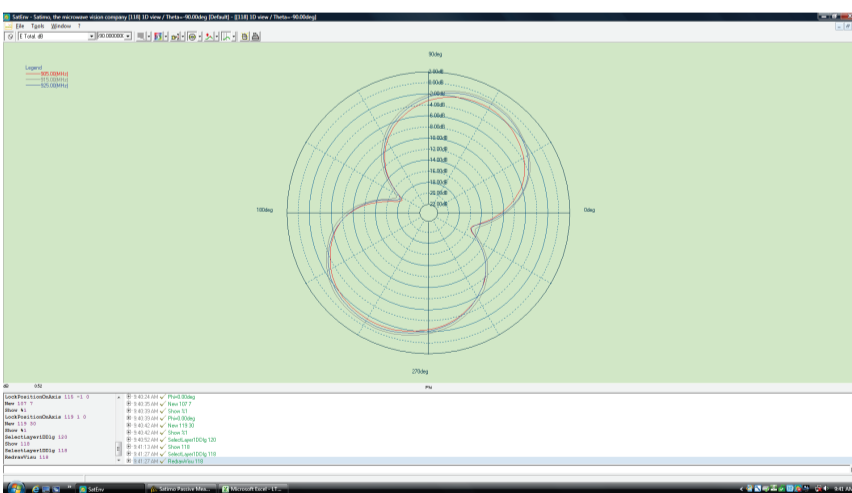


X-Z Plane

Y-Z Plane

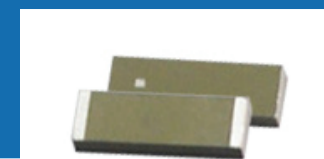


X-Y Plane



| Frequency (MHz) | 910 | 915 | 925 |
|-----------------|-------|-------|-------|
| Avg. Gain (dBi) | -2.56 | -2.12 | -2.25 |
| Peak Gain (dBi) | 3.15 | 3.42 | 3.08 |
| Efficiency (%) | 54 | 59 | 53 |

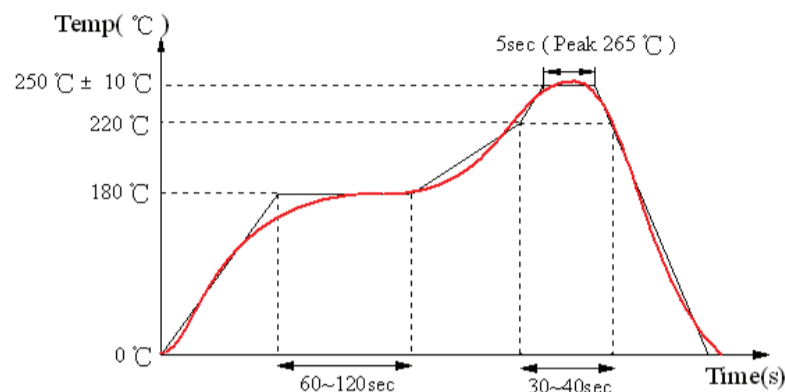
915 MHz Ceramic Chip Antenna



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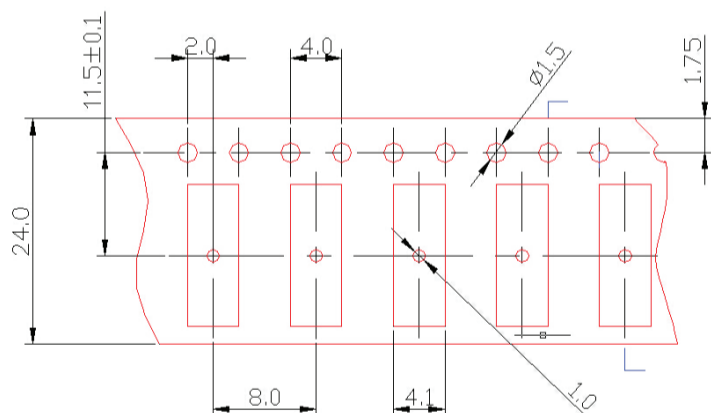
REFLOW PROFILE



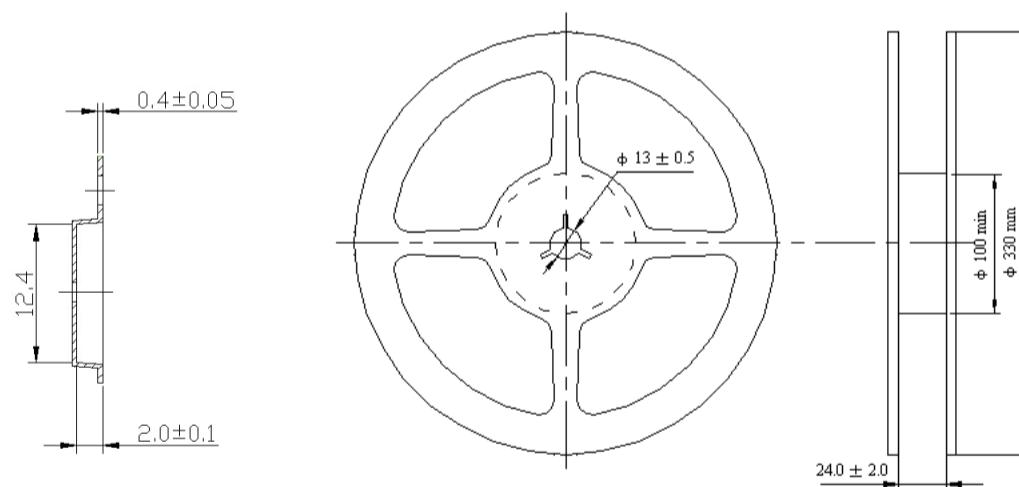
PACKAGING

| Package Type | Quantity/Size |
|--------------------|--------------------|
| Inner Box | 3000 pcs/reel |
| Carton | 15000 pcs/carton |
| Size of the carton | 345 x 250 x 360 mm |

Tape Dimensions (mm)



Reel Dimensions (mm)



Unit: mm

CAUTIONS

1. Static voltage

Static voltage between signal & ground may cause deterioration & destruction of the component. Please avoid static voltage.

2. Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning.

3. Soldering

Only leads of the component may be soldered. Please avoid soldering to any other part of the component, such as on the patterns as this will change the performance of the antenna.

Looking for pricing, stock, or lifecycle information?

Click below to explore more details on WIN SOURCE:

- [View ACAG1204-915-T on WIN SOURCE](#)
- [Abracon LLC Information](#)

Optimize Your Supply Chain with WIN SOURCE Solutions

- ✓ Global Sourcing Solution
- ✓ Obsolete Management
- ✓ Cost Control Management
- ✓ Shortage Management
- ✓ Alternative Solution
- ✓ Excess Inventory Management